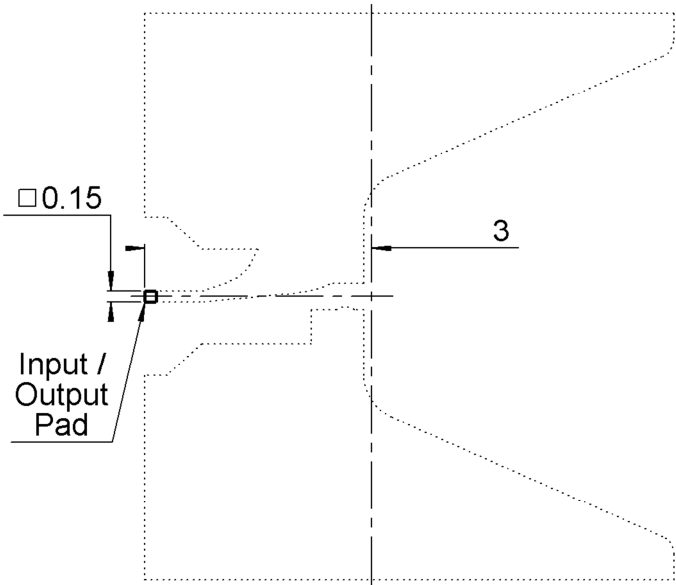




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□0.15

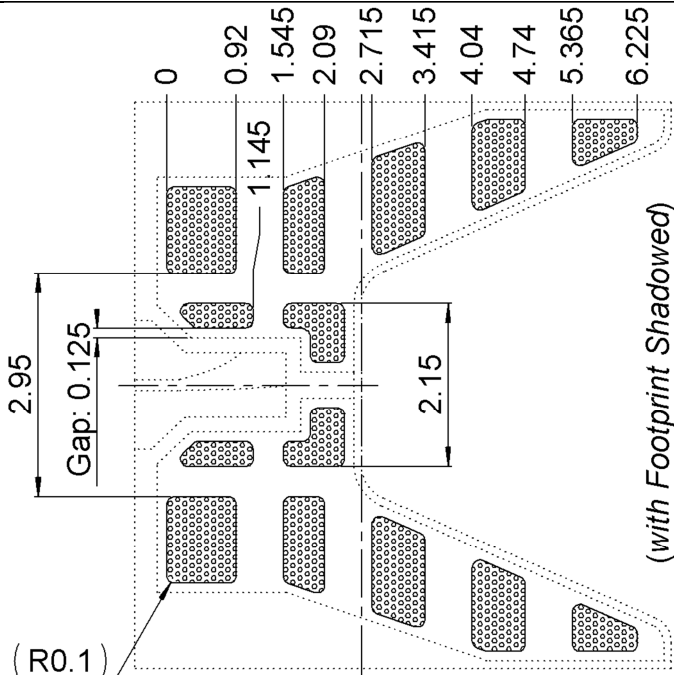
3

Input / Output Pad

(w. Layer 1 Shadowed)

Input / Output Pad

This pad is to be overlapped by the 50 ohms trace going from/towards the chip.



0 0.92 1.545 2.09 2.715 3.415 4.04 4.74 5.365 6.225

1.145

2.95

Gap: 0.125

2.15

(R0.1)

(with Footprint Shadowed)

Solder Paste

Thickness between 80 and 100µm recommended.
Use standard lead-free solder paste (SnAgCu)

----- : The layer can expand beyond the footprint limit